

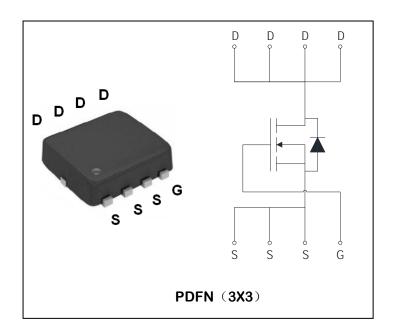
N-Channel Enhancement Mode Field Effect Transistor

PRODUCT SUMMARY

V _{DSS}	I _D	$R_{DS(ON)}$ (m Ω)
40V	40 A	5.5 m Ω

Features:

- Low Gate Charge for Fast Switching Application
- Low Rds(ON) to Minimize Conductive Loss
- 100% EAS Guaranteed
- Optimized V(BR)DSS Ruggedness
- Green Device Available



Description:

The ADM40N04Z uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

Absolute Maximum Ratings (TA = 25°C unless otherwise specifed)

Symbol	Parameter	Ratings	Unit	
Common F	Ratings			
V _{DSS}	Drain-Source Voltage		40	V
V _{GSS}	Gate-Source Voltage		±20	V
TJ	Maximum Junction Temperature		150	°C
T _{STG}	Storage Temperature Range		-55 to150	°C
ls	Diode Continuous Forward Current	T _C =25°C	40	Α
Mounted o	n Large Heat Sink			
Ідм	300µs Pulse Drain Current Tested (2)	T _C =25°C, V _{GS} =10V	120	Α
1-	Continuous Drain Current (1)	T _C =25°C, V _{GS} =10V	40	Α
lσ		T _C =100°C V _{GS} =10V	32	Α
Po	Maximum Power Dissipation	T _C =25°C	65	W

Thermal Characteristics

Symbol	Parameter	Ratings	Unit
RthJC	Thermal resistance junction-case max (1)	1.92	°C/W
RthJA	Thermal resistance junction-ambient max (1)	30	°C/W



ADM40N04Z

Electrical Characteristics (TA=25°C Unless Otherwise Noted)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
On/off Charac	cteristics					
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =250uA	40			V
Inss	Zero Gate Voltage Drain Current	V _{DS} = 40V, V _{GS} =0V T _J =25°C			10	uA
VGS(th)	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =250uA	1.1	1.6	2.4	V
Igss	Gate Leakage Current	V_{GS} = $\pm 20V$, V_{DS} = $0V$			±100	nA
Decrees	Drain-SourceOn-stateResistance(2)	V _{GS} = 10V, I _{DS} =30A		5.5	7	mΩ
RDS(ON)		V _{GS} = 4.5V, I _{DS} =20A		9	12	
Dynamic Chara	acteristics					
Ciss	Input Capacitance	V _{GS} =0V,		980		
Coss	Output Capacitance	V _{DS} = 20V,		160		pF
Crss	Reverse Transfer Capacitance	Frequency=1.0MHz		80		
Switching Char	racteristics					
td(ON)	Turn-on Delay Time(1)	V _{DD} =20V,		6		
t r	Turn-on Rise Time(1)	I _D = 20A, V _{GS} = 10V,		10		
td(OFF)	Turn-off Delay Time(1)	R _{GEN} =4.7 Ω		24		ns
t f	Turn-off Fall Time(1)			5		
Qg	Total Gate Charge(1)	V _{DS} =32V, V _{GS} = 10V,		18	23	
Qgs	Gate-Source Charge(1)	I _{DS} =20A		2.5		nC
Qgd	Gate-Drain Charge(1)			5		
Avalanche Ch	aracteristics			-	•	
		V _{DD} =24V,L=0.5mH ,V _{GS} =10				
EAS	Single Pulse Avalanche Energy (3)	$V,R_g=50\Omega$, IAS=13A		50		mJ
		T _J =25°C				
Diode Charact	eristics					
Vsp	Diode Forward Voltage(2)	I _{SD} = 20A, V _{GS} = 0 ,T _J =25°C			1.2	V

NOTES:

- 1. Surface Mounted on FR4 Board, $t \le 10$ sec.
- 2.The data tested by pulsed , pulse width $\,\leq\,\,300\text{us}$, duty cycle $\,\leq\,\,2\%$
- 3. The Min. value is 100% EAS tested guarantee.



Typical Performance Characteristics

Figure 1: On-Region Characteristics

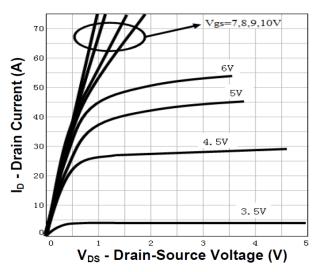


Figure 3:Drain-Source On Resistance

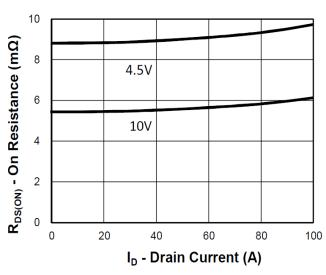


Figure 5:Maximum Continuous Drain Current v.s. Ambient Temperature

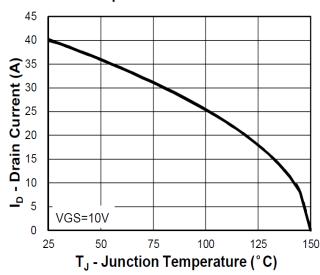


Figure 2: Normalized RDSON vs.TJ

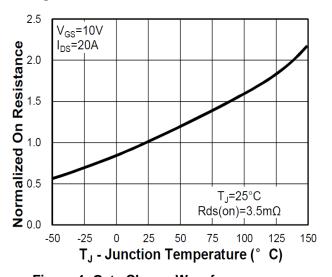


Figure 4: Gate Charge Waveform

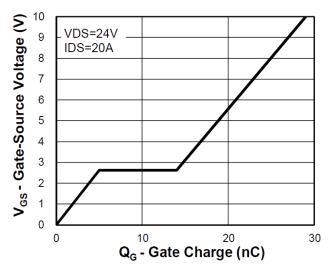


Figure 6: Maximum Safe Operation Area

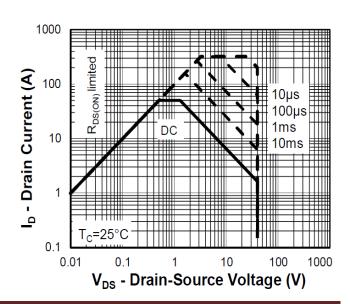




Figure 7: Capacitance vs Vds

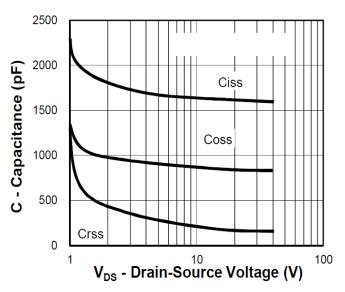


Figure 8: Typical Source-Drain Diode Forward Voltage

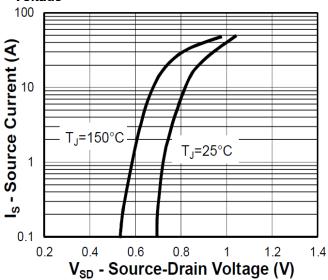
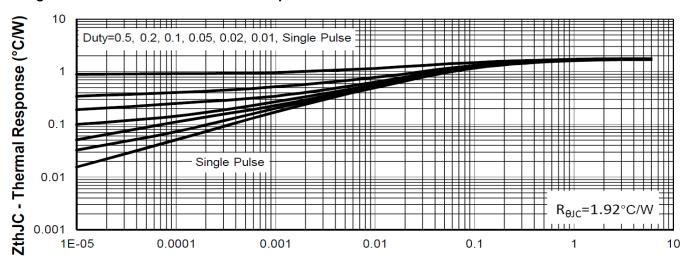


Figure 9: Effective Transient Thermal Impedance



Square Wave Pulse Duration (sec)

Figure 10: Switching Time Waveform

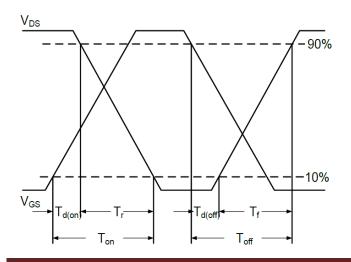
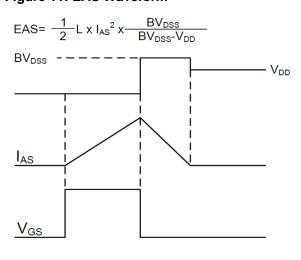
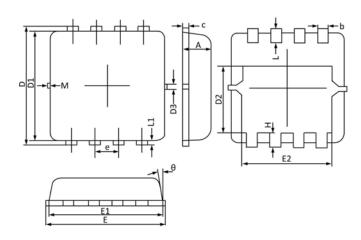


Figure 11: EAS Waveform





PACKAGE MECHANICAL DATA PDFN (3X3) Package Dimension



Symb	Dimensions In		Dimensions In		
ol	Millimeters		Inches		
Oi	Min.	Max.	Min.	Max.	
Α	0.700	0.800	0.028	0.031	
b	0.250	0.350	0.010	0.013	
С	0.100	0.250	0.004	0.009	
D	3.250	3.450	0.128	0.135	
D1	3.000	3.200	0.119	0.125	
D2	1.780	1.980	0.070	0.077	
D3	0.130REF		0.005REF		
E	3.200	3.400	0.126	0.133	
E1	3.000	3.200	0.119	0.125	
E2	2.390	2.590	0.094	0.102	
Н	0.300	0.500	0.011	0.019	
М	0.150	0.150REF 0.006REF		REF	
е	0.650 TYP.		0.026	0.026 TYP.	
L	0.300	0.500	0.011	0.019	
L1	0.130REF		0.005REF		
θ	0°	12°	0°	12°	

Ordering information

Part number	Package	Marking	Packing	Quantity
ADM40N04Z	PDFN3*3	M40N04Z	Embossed tape	5000pcs





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